L Number	Hits	Search Text	DB	Time stamp
1	1	("4383886").PN.	USPAT	2003/06/29
2	1	("4700467").PN.	USPAT	2003/06/29
3	60	wafer with (wafer and (joints or joint) and etch)	USPAT; US-PGPUB; EPO; JPO;	17:22 2003/06/29 17:24
4	40	(wafer with (wafer and (joints or joint) and etch)) and (@ad<20001102)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:52
5	0	batch adj transfer adj wafer	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 17:32
6	2670	transfer adj wafer	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/06/29 17:32
7	2046	(transfer adj wafer) and (@ad<20001102)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29
8	709	((transfer adj wafer) and (@ad<20001102)) and (etch or etchant or etching)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:12
9	16444	(mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:49
10	10897	actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:04
11	8810	(@ad<20001102) (((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29
12	1148	((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29
13	369	(bump or joint or joints or bumps) ((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and ((bump or joint or joints or bumps) with (wafer or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:22

11	T 633		**************************************	1 2002 (06/20
14	531	((((mems or microelectromechanical or	USPAT;	2003/06/29
1	į.	actuator or mirror or mirrors or	US-PGPUB;	18:39
1		micromachining or ((opto or optical) near	EPO; JPO;	i
1		(device or devices))) and (etch or	DERWENT;	}
(1	etchant or etching) and wafer) and	IBM TDB	ļ
((@ad<20001102)) and semiconductor) and	1011_100	1
ĺ			1	1
ì		(bump or joint or joints or bumps)) and	1	}
1		transfer	l	\
15	201	((((mems or microelectromechanical or	USPAT;	2003/06/29
		actuator or mirror or mirrors or	US-PGPUB;	18:39
		micromachining or ((opto or optical) near	EPO; JPO;	
	1	(device or devices))) and (etch or	DERWENT;	
1	}	etchant or etching) and wafer) and	IBM TDB	d.
	1		1011_100	
	1	(@ad<20001102)) and semiconductor) and	1	
		((bump or joint or joints or bumps) with	1	}
1	İ	(wafer or semiconductor))) not (((((mems	ļ	
	1	or microelectromechanical or actuator or	1	ļ
	ĺ.	mirror or mirrors or micromachining or	ì	1
		((opto or optical) near (device or	i	i
	ì	devices))) and (etch or etchant or	1	i
	i			
1	1	etching) and wafer) and (@ad<20001102))	1	l
1	(and semiconductor) and (bump or joint or	1	1
1 .		joints or bumps)) and transfer)	ì	ĺ
16	133	438/459.ccls. and ((mems or	USPAT;	2003/06/29
1	1	microelectromechanical or actuator or	US-PGPUB;	19:02
1	1	mirror or mirrors or micromachining or	EPO; JPO;	1
1	l	((opto or optical) near (device or	DERWENT;	
1	1 .	(devices))) and (etch or etchant or	IBM TDB)
1		etching) and (wafer or substrate))	1011_100	,
1 7	0.4	1		0000 (00 (00
17	94	((((((((((((((((((((USPAT;	2003/06/29
		microelectromechanical or actuator or	US-PGPUB;	18:53
1		mirror or mirrors or micromachining or	EPO; JPO;	
1	}	((opto or optical) near (device or	DERWENT;	
1	1	devices))) and (etch or etchant or	IBM TDB	ļ
Į.	}	etching) and (wafer or substrate))) and		
		(@ad<20001102))
18	11	,	USPAT	2002/06/20
10	1 11	3330034.0KPN.	USPAI	2003/06/29
1.0	00	100/450 3 3/4		18:59
19	92	438/459.ccls. and ((mems or	USPAT;	2003/06/29
		microelectromechanical or actuator or	US-PGPUB;	19:30
]	1	mirror or mirrors or micromachining or	EPO; JPO;	1
))	((opto or optical) near (device or	DERWENT;	1
	}	devices))) and soi)	IBM TDB	
20	72		USPAT;	2003/06/29
	'~	microelectromechanical or actuator or	US-PGPUB;	19:04
	1	mirror or mirrors or micromachining or	1	13.04
	j l		EPO; JPO;	
}	1	((opto or optical) near (device or	DERWENT;	{
	(,)	devices))) and soi)) and (@ad<20001102)	IBM_TDB	
21	0	6455398.URPN.	USPAT	2003/06/29
				19:08
22) 0)	6455398.URPN.	USPAT	2003/06/29
1	1			19:08
23	21	("5281834" "5346848" "5373184"	USPAT	2003/06/29
	1 1	"5386137" "5407856" "5472914"	OSEKI	
]		}	19:08
) 1	"5502316" "5503704" "5523602"		1
	}	"5557120" "5606186" "5728623"		!
[]	"5728624" "5849627" "5858855"		ļ
1] !	"5966622" "6004867" "6030884"	1	
]]	"6074892" "6153495" "6180496").PN.	}	j
24	63	438/458.ccls. and ((mems or	USPAT;	2003/06/29
l	1	microelectromechanical or actuator or	US-PGPUB;	19:37
1	1	mirror or mirrors or micromachining or		19.31
1] !	((opto or optical) near (device or	EPO; JPO;	Ì
1		TODEO OF ODELCAL) HEAR (GEVICE OR	DERWENT;	i i
1] !	devices))) and soi)	IBM TDB	į l

25	63	(438/458.ccls. and ((mems or	USPAT;	2003/06/29
	1	microelectromechanical or actuator or	US-PGPUB;	19:44
	}	mirror or mirrors or micromachining or	EPO; JPO;	
{	ŀ	((opto or optical) near (device or	DERWENT;	j
1	1	devices))) and soi)) not (("5281834"	IBM TDB	1
}	}	"5346848" "5373184" "5386137"	1011-100	(
i	j		Ì	(
j	}	"5407856" "5472914" "5502316" "55023704" "5522623" "55522316"	!	}
}	Į.	"5503704" "5523602" "5557120"		}
l	("5606186" "5728623" "5728624"	{	i
Į.	1	"5849627" "5858855" "5966622"	{	1
}	1	"6004867" "6030884" "6074892"	}	1
	1	"6153495" "6180496").PN.)	}	}
26	4	,	USPAT;	2003/06/29
}		microelectromechanical or actuator or	US-PGPUB;	19:32
Ì		mirror or mirrors or micromachining or	EPO; JPO;	1
1		((opto or optical) near (device or	DERWENT;	1
!	ı	devices))) and soi)) not (("5281834"	IBM TDB	i i
Į	1	"5346848" "5373184" "5386137"	-	1
Į.	1	"5407856" "5472914" "5502316"		
}		"5503704" "5523602" "5557120")	
1	1	"5606186" "5728623" "5728624"		
1	1	"5849627" "5858855" "5966622"	}	1
}	Į.	"6004867" "6030884" "6074892"		<u> </u>
1	1	"6153495" "6180496").PN.)) and ((ball		1
Į.	}	or bump or joint) and (@ad<20001102))		1
27	36		USPAT;	2003/06/29
1 - 1	1	or joint) and (@ad<20001102)		
}	1	or joint, and (ead(20001102)	US-PGPUB;	19:55
1	1		EPO; JPO;	1
}	i		DERWENT;	1
1 00	1	400/450	IBM_TDB	
28	38	/	USPAT;	2003/06/29
ł	1	or joint) and (@ad<20001102)	US-PGPUB;	20:04
1	}		EPO; JPO;) [
}			DERWENT;	}
<u> </u>			IBM_TDB	1
29	32		USPAT;	2003/06/29
1		bump or joint) and (@ad<20001102)) not	US-PGPUB;	19:44
1		(438/458.ccls. and wafer and (ball or	EPO; JPO;	j
l	(bump or joint) and (@ad<20001102))	DERWENT;	1
1	1		IBM TDB	1
31	21	((438/459.ccls. and wafer and (ball or	USPAT;	2003/06/29
1		bump or joint) and (@ad<20001102)) not	US-PGPUB;	20:01
)	(438/458.ccls. and wafer and (ball or	EPO; JPO;	1
1		bump or joint) and (@ad<20001102))) and	DERWENT;	1
1		((etch or etching or etchant) with wafer)	IBM TDB	1
32	1678	((etch or etching or etchant) with wafer)	USPAT;	2003/06/29
_]	and indium	US-PGPUB;	20:01
		The second secon	EPO; JPO;	20.01
]
			DERWENT;	1
33	1207	//letch or otching on otchint	IBM_TDB	2003/06/20
33	1207	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/06/29
	(wafer) and indium) and (@ad<20001102)	US-PGPUB;	20:02
ĺ			EPO; JPO;	1
!			DERWENT;	}
1 2 4	1		IBM_TDB	1
34	1078	((((etch or etching or etchant) with	USPAT;	2003/06/29
1]	wafer) and indium) and (@ad<20001102))	US-PGPUB;	20:04
1]]	and semiconductor	EPO; JPO;	{
]	1		DERWENT;	{
]	[]		IBM TDB	
35	192	((((etch or etching or etchant) with	USPAT;	2003/06/29
ĺ	1	wafer) and indium) and (@ad<20001102))	US-PGPUB;	20:05
	j l	and semiconductor) and (ball or bump or	EPO; JPO;	
	1 1	joint)	DERWENT;	
	j i		IBM TDB	.
				